

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet

SOD-523



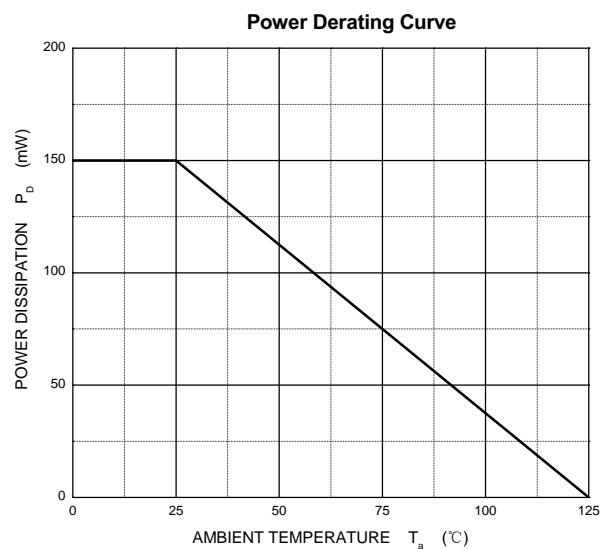
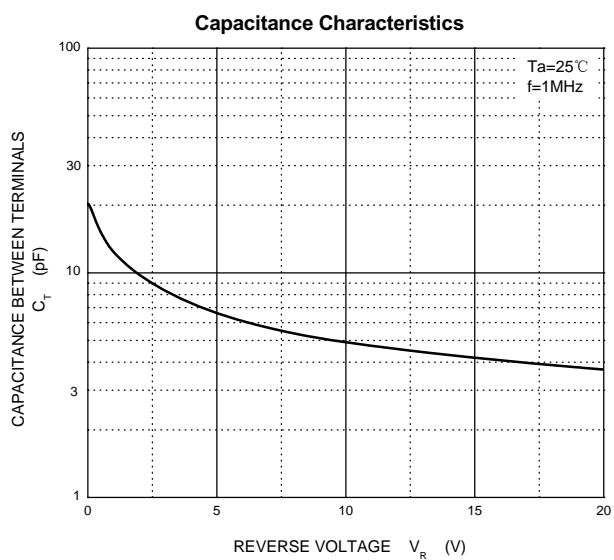
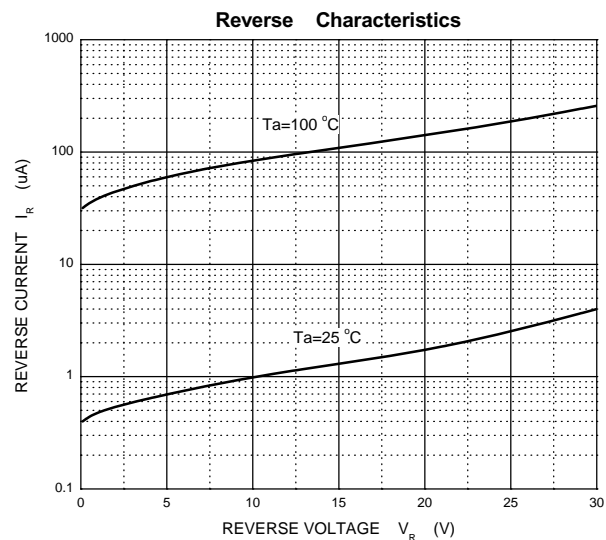
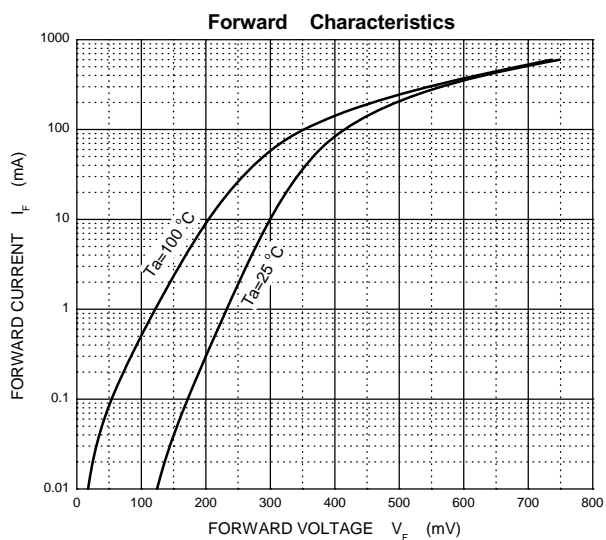
RB520S-30 Schottky barrier Diode

FEATURES

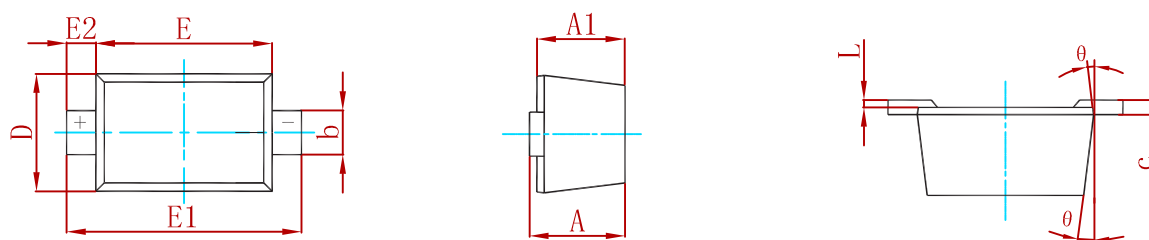
- Small surface mounting type
- Low I_R
- High reliability

Maximum Ratings and Electrical Characteristics, Single Diode @Ta=25°C

Parameter	Symbol	Limit	Unit
DC reverse voltage	V_R	30	V
Mean rectifying current	I_O	200	mA
Peak forward surge current	I_{FSM}	1	A
Power dissipation	P_D	150	mW
Thermal resistance junction to ambient	$R_{\theta JA}$	667	°C/W
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55~+150	°C

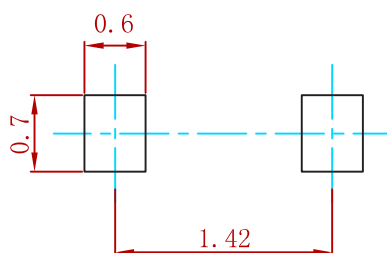


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008 REF	
L	0.010	0.070	0.001	0.003
θ	7° REF		7° REF	

Suggested Pad Layout



Note:

1. Controlling dimension: In millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
RB520S-30	SOD-523	3000

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